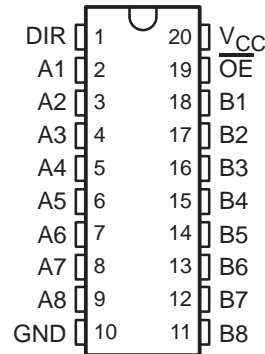


# SN74LVCZ245A OCTAL BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCES275G – JUNE 1999 – REVISED AUGUST 2003

- Operates From 2.7 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max  $t_{pd}$  of 6.3 ns at 3.3 V
- Typical  $V_{OLP}$  (Output Ground Bounce) <0.8 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot) >2 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- $I_{off}$  and Power-Up 3-State Support Hot Insertion
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V  $V_{CC}$ )
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II

DB, DW, N, NS, OR PW PACKAGE  
(TOP VIEW)



## description/ordering information

This octal bus transceiver is designed for 2.7-V to 3.6-V  $V_{CC}$  operation.

The SN74LVCZ245A is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ( $\overline{OE}$ ) input can be used to disable the device so the buses are effectively isolated.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

When  $V_{CC}$  is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for hot-insertion applications using  $I_{off}$  and power-up 3-state. The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 20	SN74LVCZ245AN	SN74LVCZ245AN
	SOIC – DW	Tube of 25	SN74LVCZ245ADW	LVCZ245A
		Reel of 2000	SN74LVCZ245ADWR	
	SOP – NS	Reel of 2000	SN74LVCZ245ANSR	LVCZ245A
	SSOP – DB	Reel of 2000	SN74LVCZ245ADBR	CV245A
	TSSOP – PW	Tube of 70	SN74LVCZ245APW	CV245A
		Reel of 2000	SN74LVCZ245APWR	CV245A
Reel of 250		SN74LVCZ245APWT	CV245A	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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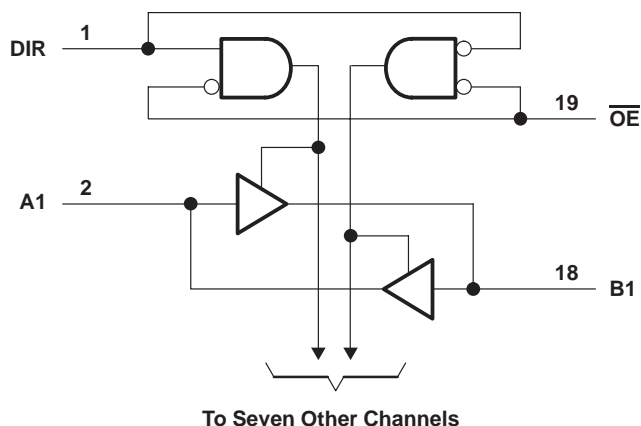
**SN74LVCZ245A**  
**OCTAL BUS TRANSCEIVER**  
**WITH 3-STATE OUTPUTS**

SCES275G – JUNE 1999 – REVISED AUGUST 2003

**FUNCTION TABLE**

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

**logic diagram (positive logic)**



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$ .....	-0.5 V to 6.5 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to 6.5 V
Voltage range applied to any output in the high-impedance or power-off state, $V_O$ (see Note 1) .....	-0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, $V_O$ (see Notes 1 and 2) .....	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	-50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ ) .....	-50 mA
Continuous output current, $I_O$ .....	$\pm 50$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 100$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 3): DB package .....	70°C/W
DW package .....	58°C/W
N package .....	89°C/W
NS package .....	60°C/W
PW package .....	83°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 2. The value of  $V_{CC}$  is provided in the recommended operating conditions table.  
 3. The package thermal impedance is calculated in accordance with JESD 51-7.

**SN74LVCZ245A**  
**OCTAL BUS TRANSCEIVER**  
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**recommended operating conditions (see Note 4)**

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		2.7	3.6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V	2		V
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V		0.8	V
V <sub>I</sub>	Input voltage		0	5.5	V
V <sub>O</sub>	Output voltage	High or low state	0	V <sub>CC</sub>	V
		3-state	0	5.5	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2.7 V		-12	mA
		V <sub>CC</sub> = 3 V		-24	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.7 V		12	mA
		V <sub>CC</sub> = 3 V		24	
Δt/Δv	Input transition rise or fall rate			6	ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate		150		μs/V
T <sub>A</sub>	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP†	MAX	UNIT
V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	2.7 V to 3.6 V	V <sub>CC</sub> -0.2			V
	I <sub>OH</sub> = -12 mA	2.7 V	2.2			
		3 V	2.4			
	I <sub>OH</sub> = -24 mA	3 V	2.2			
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	2.7 V to 3.6 V			0.2	V
	I <sub>OL</sub> = 12 mA	2.7 V			0.4	
	I <sub>OL</sub> = 24 mA	3 V			0.55	
I <sub>I</sub>	Control inputs V <sub>I</sub> = 0 to 5.5 V	3.6 V			±5	μA
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0			±5	μA
I <sub>OZ</sub> ‡	V <sub>O</sub> = 0 to 5.5 V	3.6 V			±5	μA
I <sub>OZPU</sub>	V <sub>O</sub> = 0.5 V to 2.5 V, $\overline{OE}$ = don't care	0 to 1.5 V			±5	μA
I <sub>OZPD</sub>	V <sub>O</sub> = 0.5 V to 2.5 V, $\overline{OE}$ = don't care	1.5 V to 0			±5	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V			100	μA
	3.6 V ≤ V <sub>I</sub> ≤ 5.5 V§					
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V			100	μA
C <sub>i</sub>	Control inputs V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		4		pF
C <sub>io</sub>	A or B ports V <sub>O</sub> = V <sub>CC</sub> or GND	3.3 V		6		pF

† All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

‡ For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

§ This applies in the disabled state only.



**SN74LVCZ245A**  
**OCTAL BUS TRANSCEIVER**  
**WITH 3-STATE OUTPUTS**

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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	B or A		7.3	1.5	6.3	ns
t <sub>en</sub>	$\overline{OE}$	A or B		9.5	1.5	8.5	ns
t <sub>dis</sub>	$\overline{OE}$	A or B		8.5	1.7	7.5	ns

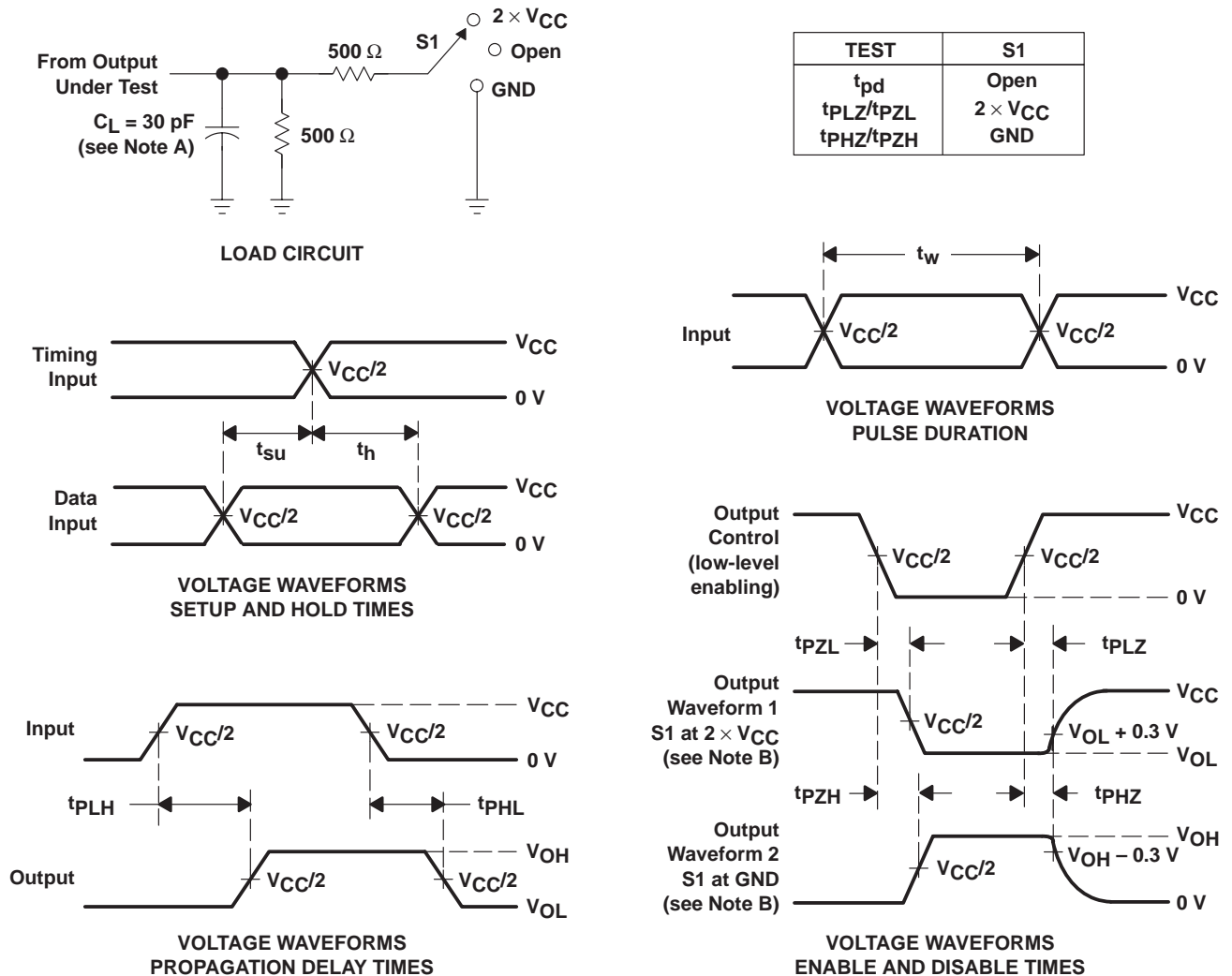
operating characteristics, T<sub>A</sub> = 25°C

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 3.3 V	UNIT
			TYP	
C <sub>pd</sub>	Power dissipation capacitance per transceiver	Outputs enabled	42	pF
		Outputs disabled	3	



PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 2.7\text{ V AND } 3.3\text{ V} \pm 0.3\text{ V}$



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 2\text{ ns}$ ,  $t_f \leq 2\text{ ns}$ .
  - D. The outputs are measured one at a time with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVCZ245ADBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CV245A	<a href="#">Samples</a>
SN74LVCZ245ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVCZ245A	<a href="#">Samples</a>
SN74LVCZ245ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVCZ245A	<a href="#">Samples</a>
SN74LVCZ245APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CV245A	<a href="#">Samples</a>
SN74LVCZ245APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CV245A	<a href="#">Samples</a>
SN74LVCZ245APWT	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CV245A	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVCZ245ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74LVCZ245ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LVCZ245ANSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74LVCZ245APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVCZ245ADBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74LVCZ245ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LVCZ245ANSR	SO	NS	20	2000	367.0	367.0	45.0
SN74LVCZ245APWR	TSSOP	PW	20	2000	367.0	367.0	38.0

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

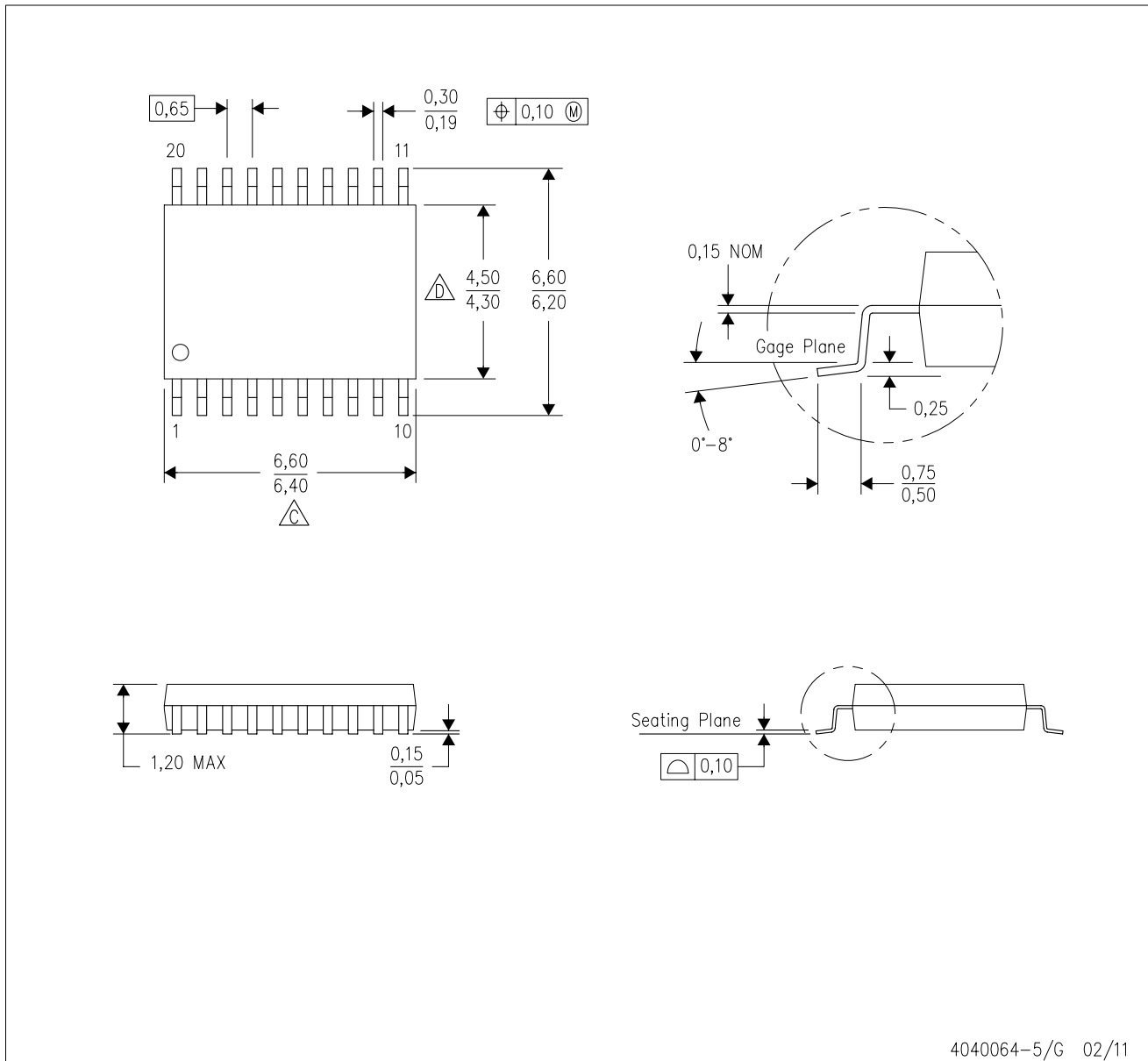
14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

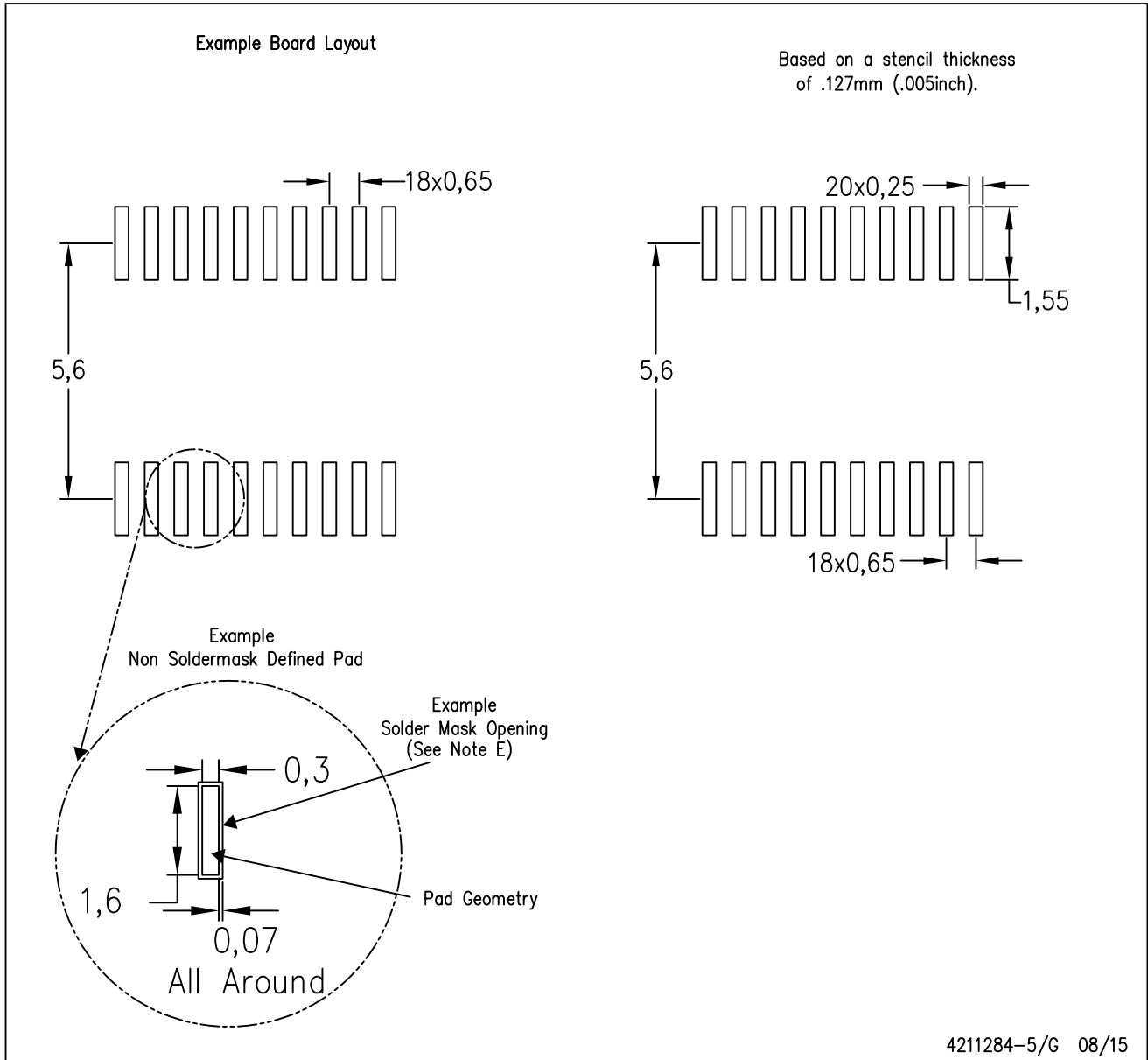


4040064-5/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

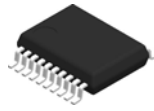
PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

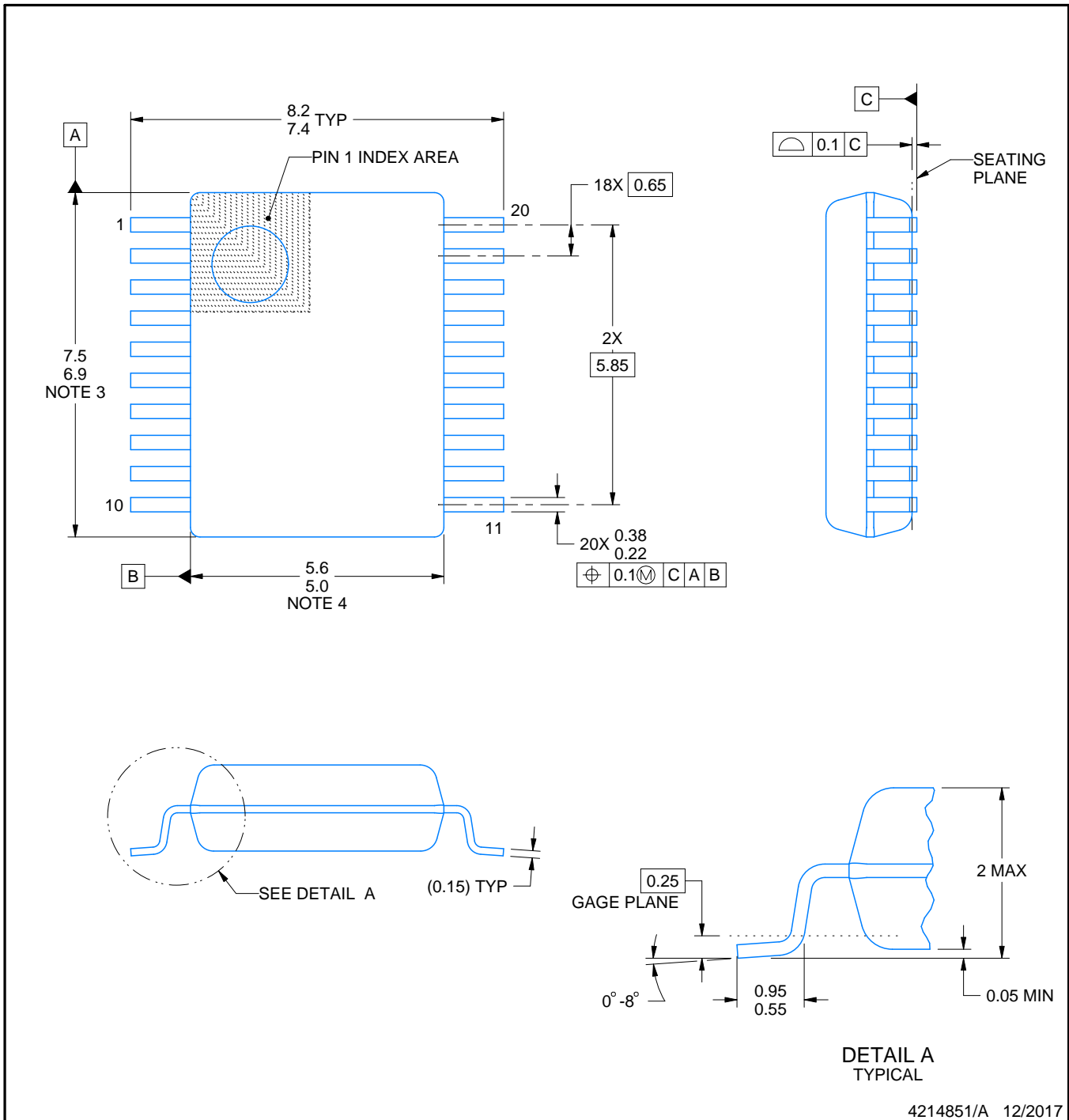
# DB0020A



# PACKAGE OUTLINE

## TSSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4214851/A 12/2017

### NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

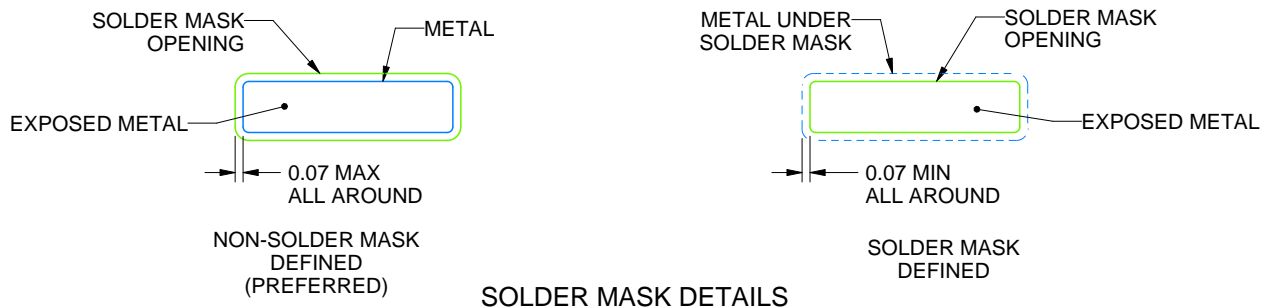
DB0020A

TSSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4214851/A 12/2017

NOTES: (continued)

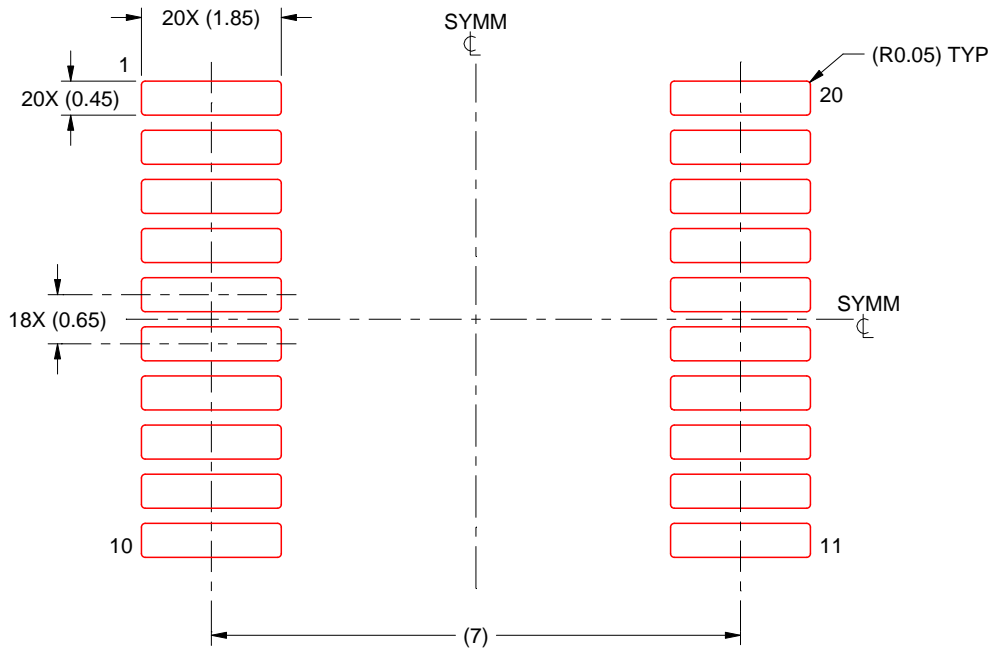
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DB0020A

TSSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4214851/A 12/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# DW0020A



# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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